

# 8-Channel Serial-to-Parallel Converter with High-Voltage Push-Pull Outputs, Polarity, Hi-Z and Short-Circuit Detect

#### **Features**

- · Up to 250V Output Voltage
- · Low-Power Level Shifting from 5V to 250V
- · Shift Register Speed:
  - 8 MHz at V<sub>DD</sub> = 5V
- · Latched Data Outputs
- · Output Polarity and Blanking
- · Output Short-Circuit Detect
- · Output High-Z (Hi-Z) Control
- · CMOS-Compatible Inputs

## **Applications**

- · Piezoelectric Transducer Driver
- · Braille Driver
- · Weaving Applications
- · Printer Drivers
- · Microelectromechanical Systems Applications
- Displays

## **General Description**

The HV513 is a low-voltage-to-high-voltage serial-to-parallel converter with eight high-voltage push-pull outputs. This device is designed to drive small capacitive loads such as piezoelectric transducers. It can also be used in any application requiring multiple high-voltage outputs with medium-current source-and-sink capabilities.

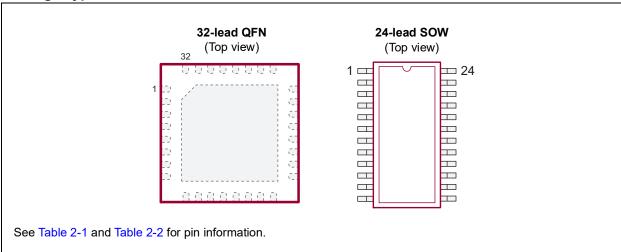
The device consists of an 8-bit Shift register, eight latches and control logic to perform the polarity select and blanking of the outputs. Data is shifted through the Shift register on the low-to-high transition of the clock. A data output buffer is provided for cascading devices. The operation of the Shift register is not affected by the latch enable (LE), blanking (BL), polarity (POL) and Hi-Z control inputs. The transfer of data from the Shift register to the latch occurs when the LE is high. The data in the latch is stored when LE is low. A Hi-Z pin is provided to set all the outputs in a High-Z state.

All outputs have short-circuit protection that detects if the outputs have reached the required output state. If <u>an output</u> does not track the required state, then the <u>SHORT</u> pin will be low. This output will pulse low during the output transition period under normal operation. See Figure 3-2 for details.

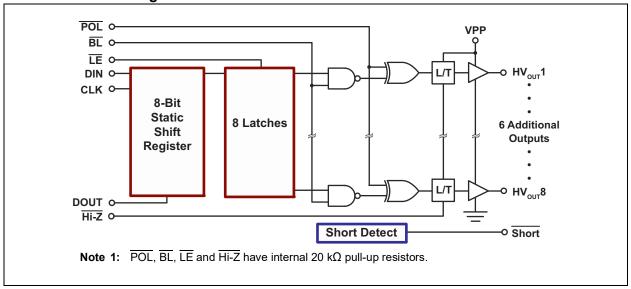
All outputs will have a break-before-make circuitry to reduce crossover current during output state changes.

The  $\overline{POL}$ ,  $\overline{BL}$ ,  $\overline{LE}$  and  $\overline{Hi-Z}$  inputs have an internal pull-up resistor.

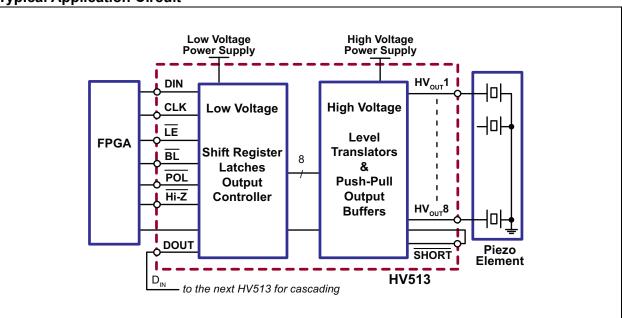
## **Package Types**



## **Functional Block Diagram**



## **Typical Application Circuit**



## 1.0 ELECTRICAL CHARACTERISTICS

## **Absolute Maximum Ratings†**

Logic Supply Voltage, V <sub>DD</sub>	–0.5V to +6V
High-Voltage Supply, V <sub>PP</sub>	V <sub>DD</sub> to +275V
Logic Input Levels	–0.5V to V <sub>DD</sub> +0.5V
Ground Current (Note 1)	
High-Voltage Supply Current (Note 1)	0.25A
Maximum Junction Temperature, T <sub>J(MAX)</sub>	+125°C
Storage Temperature, T <sub>S</sub>	
Continuous Total Power Dissipation:	
32-lead QFN (Note 2)	750 mW
24-lead SOW (Note 2)	750 mW

**† Notice:** Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

- **Note 1:** Connection to all power and ground pads is required. Duty cycle is limited by the total power dissipated in the package.
  - 2: For operations above 25°C ambient, derate linearly to 85°C at 12 mW/°C.

## RECOMMENDED OPERATING CONDITIONS

Parameter	Sym.	Min.	Тур.	Max.	Unit	Conditions
Logic Supply Voltage	$V_{DD}$	4.5	5	5.5	V	
High-Voltage Supply Voltage	$V_{PP}$	50	_	250	V	Note 1
High-Level Input Voltage	V <sub>IH</sub>	V <sub>DD</sub> -0.9V	_	$V_{DD}$	V	
Low-Level Input Voltage	$V_{IL}$	0	_	0.9	V	
Operating Junction Temperature	$T_J$	-40	_	+85	°C	

**Note 1:** The output may not switch below the minimum  $V_{PP}$ .

## DC ELECTRICAL CHARACTERISTICS

Electrical Specifications: Ov	er typical ope	rating cond	litions unles	ss othe	erwise s	specifie	ed, T <sub>J</sub> = 25°C.
Parameter		Sym.	Min.	Тур.	Max.	Unit	Conditions
V <sub>DD</sub> Supply Current	I <sub>DD</sub>	_	_	4	mA	f <sub>CLK</sub> = 8 MHz, <del>LE</del> = Low	
Outroport V Committee Comment			_	_	0.1	mA	All V <sub>IN</sub> = V <sub>DD</sub>
Quiescent V <sub>DD</sub> Supply Current		I <sub>DDQ</sub>	_		2	mA	All V <sub>IN</sub> = 0V
High-Voltage Supply Current		I <sub>PP</sub>	_	_	100	μA	$V_{PP}$ = 250V, $f_{OUT}$ = 300 Hz, no load
Quiescent V <sub>PP</sub> Supply Voltage		I <sub>PPQ</sub>	_	_	100	μΑ	V <sub>PP</sub> = 240V, outputs are static
High-Level Logic Input Current		I <sub>IH</sub>	_	_	10	μΑ	$V_{IH} = V_{DD}$
			_	_	-10	μΑ	V <sub>IL</sub> = 0V
Low-Level Logic Input Current		I <sub>IL</sub>	_	_	-350	μA	V <sub>IL</sub> = 0V, for inputs with pull-up resistors
High-Level Output	HV <sub>OUT</sub>	V <sub>OH</sub>	140	_	_	٧	V <sub>PP</sub> = 200V, I <sub>HVOUT</sub> = –20 mA
·	Data Out	011	V <sub>DD</sub> –1V	_		V	I <sub>DOUT</sub> = -0.1 mA
HV <sub>OUT</sub>		\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	_	_	60	V	V <sub>DD</sub> = 4.5V, I <sub>HVOUT</sub> = 20 mA
Low-Level Output	Data Out	V <sub>OL</sub>	_	_	1	V	I <sub>DOUT</sub> = -0.1 mA

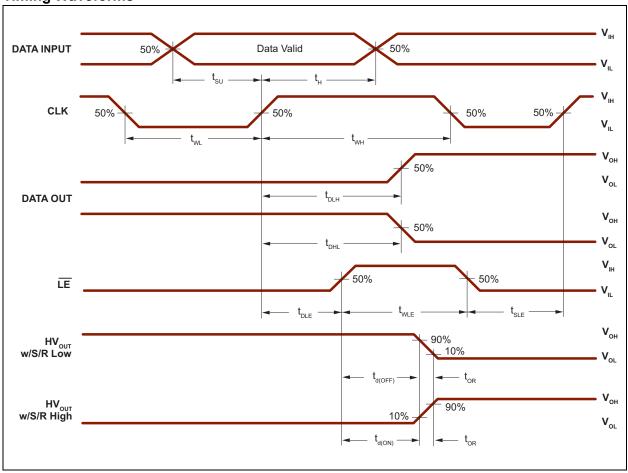
## **AC ELECTRICAL CHARACTERISTICS**

Electrical Specifications: Over typical open	rating cond	itions unle	ss othe	erwise	specifie	ed, T <sub>J</sub> = 25°C.
Parameter	Sym.	Min.	Тур.	Max.	Unit	Conditions
Clock Frequency	f <sub>CLK</sub>	0	_	8	MHz	
Output Switching Frequency (SOA Limited)	f <sub>OUT</sub>	I	300	_	Hz	$C_L = 50 \text{ nF}, V_{PP} = 200V$
Clock Width High and Low	$t_{WL}$ , $t_{WH}$	62	_	_	ns	
Data Set-Up Time before Clock Rises	t <sub>SU</sub>	15	_		ns	
Data Hold Time after Clock Rises	t <sub>H</sub>	30	_	_	ns	
Latch Enable Pulse Width	t <sub>WLE</sub>	80	_	_	ns	
Latch Enable Delay Time after Rising Edge of Clock	t <sub>DLE</sub>	35	_	_	ns	
Latch Enable Set-Up Time before Clock Rises	t <sub>SLE</sub>	40	_	_	ns	
HV <sub>OUT</sub> Rise/Fall Time	t <sub>OR</sub> , t <sub>OF</sub>	_	_	1000	μs	C <sub>L</sub> = 100 nF, V <sub>PP</sub> = 200V
Delay Time for Output to Start Rise/Fall	t <sub>dON/OFF</sub>	-	_	500	ns	
Delay Time Clock to Data Low to High	t <sub>DLH</sub>	_	_	110	ns	C <sub>L</sub> = 15 pF
Delay Time Clock to Data High to Low	t <sub>DHL</sub>	_	_	110	ns	C <sub>L</sub> = 15 pF
All Logic Inputs	t <sub>r</sub> , t <sub>f</sub>	_	_	5	ns	
Output Short-Circuit Detection	t <sub>SD</sub>	_	_	500	ns	$C_L = 15 \text{ pF}$ , short to output fall of SHORT
Output Short-Circuit Clear	t <sub>SC</sub>	_	_	3000	ns	Short clear to output rise of SHORT
Output High-Z State	t <sub>HI-Z</sub>	_	_	500	ns	

## **TEMPERATURE SPECIFICATIONS**

Parameter	Sym.	Min.	Тур.	Max.	Unit	Conditions
TEMPERATURE RANGE						
Operating Junction Temperature	$T_J$	-40	_	+85	°C	
Maximum Junction Temperature	$T_{J(MAX)}$	_	_	+125	°C	
Storage Temperature	T <sub>S</sub>	-65	_	+150	°C	
PACKAGE THERMAL RESISTANCE						
32-lead QFN	$\theta_{JA}$	_	22		°C/W	
24-lead SOW	$\theta_{\sf JA}$	_	44	_	°C/W	

**Timing Waveforms** 



## 2.0 PIN DESCRIPTION

The details on the pins of HV513 32-lead QFN and 24-lead SOW packages are listed in Table 2-1 and Table 2-2, respectively. Refer to **Package Types** for the location of pins.

TABLE 2-1: 32-LEAD QFN PIN FUNCTION TABLE

Pin Number	Pin Name	Description					
1	NC	No connection					
2	NC	No connection					
3	NC	No connection					
4	LGND	Low-voltage ground					
5	HVGND	High-voltage ground					
6	HVGND	High-voltage ground					
7	NC	No connection					
8	NC	No connection					
9	HVOUT1	High-voltage push-pull output					
10	HVOUT2	High-voltage push-pull output					
11	HVOUT3	High-voltage push-pull output					
12	HVOUT4	High-voltage push-pull output					
13	HVOUT5	High-voltage push-pull output					
14	HVOUT6	High-voltage push-pull output					
15	HVOUT7	High-voltage push-pull output					
16	HVOUT8	High-voltage push-pull output					
17	NC	No connection					
18	NC	No connection					
19	VPP	High-voltage supply					
20	VPP	High-voltage supply					
21	VDD	Logic supply voltage					
22	DOUT	Data output					
23	NC	No connection					
24	NC	No connection					
25	BL	Blanking. A logic input low sets all HVOUTs low.					
26	NC	No connection					
27	POL	Polarity bar input logic					
28	CLK	Clock. Shift registers shift data on the rising edge of input clock.					
29	LE	Latch enable bar input logic					
30	SHORT	If output does not reach its required state, a logic '0' will be asserted at the SHORT pin.					
31	Hi-Z	High-impedance pin. Logic input low sets all outputs in a High-impedance state.					
32	DIN	Data input					
Cente	er Pad	Center Pad is at V <sub>PP</sub> potential. Connect to VPP or leave floating.					

# **HV513**

TABLE 2-2: 24-LEAD SOW PIN FUNCTION TABLE

Pin Number	Pin Name	Description
1	NC	No connection
2	VDD	Logic supply voltage
3	DOUT	Data output
4	BL	Blanking. A logic input low sets all HVOUTs low.
5	POL	Polarity bar input logic
6	CLK	Clock. Shift registers shift data on the rising edge of input clock.
7	E	Latch enable bar input logic
8	SHORT	If output does not reach its required state, a logic '0' will be asserted at the SHORT pin.
9	Hi-Z	High-impedance pin. Logic input low sets all outputs in a high-impedance state.
10	DIN	Data input
11	LGND	Low-voltage ground
12	NC	No connection
13	HVGND	High-voltage ground
14	HVGND	High-voltage ground
15	HVOUT1	High-voltage push-pull output
16	HVOUT2	High-voltage push-pull output
17	HVOUT3	High-voltage push-pull output
18	HVOUT4	High-voltage push-pull output
19	HVOUT5	High-voltage push-pull output
20	HVOUT6	High-voltage push-pull output
21	HVOUT7	High-voltage push-pull output
22	HVOUT8	High-voltage push-pull output
23	VPP	High-voltage supply
24	VPP	High-voltage supply

## 3.0 FUNCTIONAL DESCRIPTION

Follow the steps in Table 3-1 to power up and power down the HV513.

TABLE 3-1: POWER-UP AND POWER-DOWN SEQUENCE

	Power-up	Power-down				
Step	Description	Step	Description			
1	Connect ground.	1	Remove V <sub>PP.</sub>			
2	Apply V <sub>DD</sub> .	2	Remove all inputs.			
3	Set all inputs (Data, CLK, Enable, etc.) to a known state.	3	Remove V <sub>DD.</sub>			
4	Apply V <sub>PP.</sub>	4	Disconnect ground.			

**TABLE 3-2: TRUTH FUNCTION TABLE** 

			Inpu	ıts			Outputs					
Function	Data	CLK	LE	BL	POL	Hi-Z	Shift	Register	High-V	oltage Output	Data Out	
	Dala	OLK		DL	POL	пі-2	1	28	1	28	*	
All On	Х	Х	Х	L	L	Н	*	**	Н	НН	*	
All Off	Х	Х	Х	L	Н	Н	*	**	L	LL	*	
Invert Mode	Х	Х	L	Н	L	Н	*	**	*	**	*	
Load S/R	H or L	1	L	Н	Н	Н	H or L	**	*	**	*	
Store Data in	Х	Х	L	Н	Н	Н	*	**	*	**	*	
Latches	Х	Х	L	Н	L	Н	*	**	*	**	*	
Transparent	L	1	Н	Н	Н	Н	L	**	L	**	*	
Latch Mode	Н	1	Н	Н	Н	Н	Н	**	Н	**	*	
Outputs Hi-Z	Х	Х	Х	Х	Х	L	*	**	High-imp	edance outputs	*	
Outputs On	Х	Х	Х	Х	Х	Н	*	**	*	**	*	

**Note:** H = High-logic level

L = Low-logic level

X = Irrelevant

↑ = Low-to-high transition

<sup>\* =</sup> Dependent on the previous stage's state before the last CLK or last  $\overline{\text{LE}}$  high

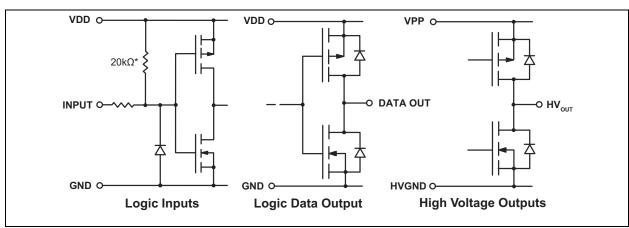


FIGURE 3-1: Input and Output Equivalent Circuits.

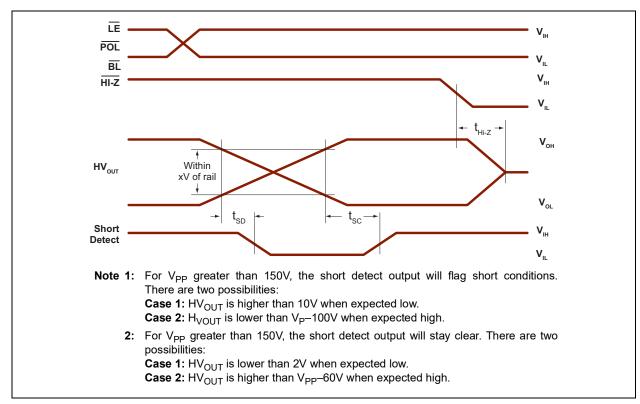
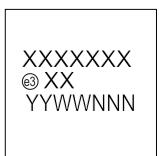


FIGURE 3-2: Short-Circuit Detect Detail Timing.

## 4.0 PACKAGE MARKING INFORMATION

## 4.1 Packaging Information

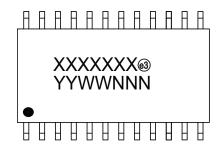
32-lead QFN



Example



24-lead SOW



Example



**Legend:** XX...X Product Code or Customer-specific information

Y Year code (last digit of calendar year)
YY Year code (last 2 digits of calendar year)
WW Week code (week of January 1 is week '01')
NNN Alphanumeric traceability code

e3 Pb-free JEDEC® designator for Matte Tin (Sn)

This package is Pb-free. The Pb-free JEDEC designator (e3)

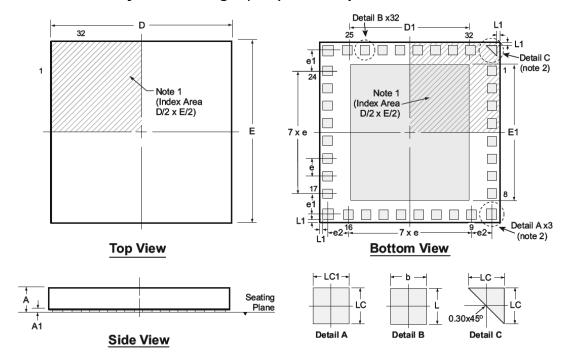
can be found on the outer packaging for this package.

Note:

In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for product code or customer-specific information. Package may or not include the corporate logo.

## 32-Lead QFN Package Outline (K7)

6.00x6.00mm body, 0.80mm height (max), 0.50mm pitch



Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.

#### Notes

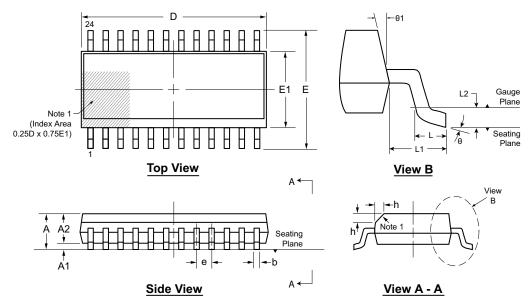
- A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.
- 2. The 4 corner pads are for mechanical placement only, they are not internally connected.

Symb	ol	Α	A1	b	D	D1	E	E1	е	e1	e2	L	L1	LC	LC1		
	MIN	0.70	0.00	0.20	5.90	3.20	5.90	4.30		0.50 1.00 BSC REF	4.00	4.00		0.20	- 1-	0.20	0.25
Dimension (mm)	NOM	0.75	-	0.30	6.00	3.30	6.00	4.40	0.50 BSC		0.975 REF	1 0.30	0.10 REF	0.30	0.35		
()	MAX	0.80	0.05	0.40	6.10	3.40	6.10	4.50	500	112	11.	0.40	1 (	0.40	0.45		

Drawings not to scale.

## 24-Lead SOW (Wide Body) Package Outline (WG)

15.40x7.50 body, 2.65mm height (max), 1.27mm pitch



Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.

1. A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.

Symbo	ol	Α	A1	A2	b	D	E	E1	е	h	L	L1	L2	θ	θ1
	MIN	2.15*	0.10	2.05	0.31	15.20*	9.97*	7.40*		0.25	0.40			0°	5°
Dimension (mm)	NOM	-	-	-	-	15.40	10.30	7.50	1.27 BSC	-	-	1.40 REF	0.25 BSC	-	-
()	MAX	2.65	0.30	2.55*	0.51	15.60*	10.63*	7.60*		0.75	1.27		230	8º	15°

JEDEC Registration MS-013, Variation AD, Issue E, Sep. 2005.
\* This dimension is not specified in the JEDEC drawing.

Drawings are not to scale.



NOTES:

## APPENDIX A: REVISION HISTORY

## **Revision A (October 2017)**

- Converted Supertex Doc # DSFP-HV513 to Microchip DS20005846B
- Removed "HVCMOS® Technology" in the Features section
- · Changed the package marking format
- Removed the 32-lead (6 x 6) WQFN K7 M935 media type
- Changed the quantity of the 32-lead (6 x 6)
   WQFN K7 package from 400/Tray to 490/Tray
- · Made minor changes throughout the document

## Revision B (June 2019)

• Added Center Pad details to Table 2-1.

## PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

PART NO.	<u>xx</u>	- <b>x</b> - <b>x</b>	Examples:
Device	Package Options	Environmental Media Type	a) HV513K7-G:  8-Channel Serial-to-Parallel Converter with High-Voltage Push-Pull Outputs, Polarity,
Device:	HV513	<ul> <li>8-Channel Serial-to-Parallel Converter with High-Voltage Push-Pull Outputs, Polarity, Hi-Z and Short-Circuit Detect</li> </ul>	Hi-Zand Short-Circuit Detect, 32-lead (6 x 6) WQFN, 490/ Tray
Packages:	K7 WG	= 32-lead (6 x 6) WQFN = 24-lead SOW	b) HV513WG-G:  8-Channel Serial-to-Parallel Converter with High-Voltage Push-Pull Outputs, Polarity, Hi-Z and Short-Circuit Detect, 24-lead SOW, 1000/Reel
Environmental:	G	= Lead (Pb)-free/RoHS-compliant Package	
Media Types:	(blank)	<ul><li>= 490/Tray for a K7 package</li><li>= 1000/Reel for a WG package</li></ul>	

### Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our
  knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data
  Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- · Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE. Microchip disclaims all liability arising from this information and its use. Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights unless otherwise stated.

#### **Trademarks**

The Microchip name and logo, the Microchip logo, Adaptec, AnyRate, AVR, AVR logo, AVR Freaks, BesTime, BitCloud, chipKIT, chipKiT logo, CryptoMemory, CryptoRF, dsPIC, FlashFlex, flexPWR, HELDO, IGLOO, JukeBlox, KeeLoq, Kleer, LANCheck, LinkMD, maXStylus, maXTouch, MediaLB, megaAVR, Microsemi, Microsemi logo, MOST, MOST logo, MPLAB, OptoLyzer, PackeTime, PIC, picoPower, PICSTART, PIC32 logo, PolarFire, Prochip Designer, QTouch, SAM-BA, SenGenuity, SpyNIC, SST, SST Logo, SuperFlash, Symmetricom, SyncServer, Tachyon, TempTrackr, TimeSource, tinyAVR, UNI/O, Vectron, and XMEGA are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

APT, ClockWorks, The Embedded Control Solutions Company, EtherSynch, FlashTec, Hyper Speed Control, HyperLight Load, IntelliMOS, Libero, motorBench, mTouch, Powermite 3, Precision Edge, ProASIC, ProASIC Plus, ProASIC Plus logo, Quiet-Wire, SmartFusion, SyncWorld, Temux, TimeCesium, TimeHub, TimeProvider, Vite, WinPath, and ZL are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Adjacent Key Suppression, AKS, Analog-for-the-Digital Age, Any Capacitor, AnyIn, AnyOut, BlueSky, BodyCom, CodeGuard, CryptoAuthentication, CryptoAutomotive, CryptoCompanion, CryptoController, dsPICDEM, dsPICDEM.net, Dynamic Average Matching, DAM, ECAN, EtherGREEN, In-Circuit Serial Programming, ICSP, INICnet, Inter-Chip Connectivity, JitterBlocker, KleerNet, KleerNet logo, memBrain, Mindi, MiWi, MPASM, MPF, MPLAB Certified logo, MPLIB, MPLINK, MultiTRAK, NetDetach, Omniscient Code Generation, PICDEM, PICDEM.net, PICkit, PICtail, PowerSmart, PureSilicon, QMatrix, REAL ICE, Ripple Blocker, SAM-ICE, Serial Quad I/O, SMART-I.S., SQI, SuperSwitcher, SuperSwitcher II, Total Endurance, TSHARC, USBCheck, VariSense, ViewSpan, WiperLock, Wireless DNA, and ZENA are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

The Adaptec logo, Frequency on Demand, Silicon Storage Technology, and Symmcom are registered trademarks of Microchip Technology Inc. in other countries.

GestIC is a registered trademark of Microchip Technology Germany II GmbH & Co. KG, a subsidiary of Microchip Technology Inc., in other countries.

All other trademarks mentioned herein are property of their respective companies.

© 2019, Microchip Technology Incorporated, All Rights Reserved.

ISBN: 978-1-5224-4693-4

For information regarding Microchip's Quality Management Systems, please visit www.microchip.com/quality.



## **Worldwide Sales and Service**

#### **AMERICAS**

Corporate Office 2355 West Chandler Blvd. Chandler, AZ 85224-6199

Tel: 480-792-7200 Fax: 480-792-7277 Technical Support:

http://www.microchip.com/

support Web Address:

www.microchip.com

Atlanta Duluth, GA

Tel: 678-957-9614 Fax: 678-957-1455

**Austin, TX** Tel: 512-257-3370

**Boston** 

Westborough, MA Tel: 774-760-0087 Fax: 774-760-0088

Chicago Itasca, IL

Tel: 630-285-0071 Fax: 630-285-0075

Dallas

Addison, TX Tel: 972-818-7423 Fax: 972-818-2924

**Detroit** Novi, MI

Tel: 248-848-4000

Houston, TX Tel: 281-894-5983

Indianapolis

Noblesville, IN Tel: 317-773-8323 Fax: 317-773-5453 Tel: 317-536-2380

Los Angeles

Mission Viejo, CA Tel: 949-462-9523 Fax: 949-462-9608 Tel: 951-273-7800

Raleigh, NC Tel: 919-844-7510

New York, NY Tel: 631-435-6000

**San Jose, CA** Tel: 408-735-9110 Tel: 408-436-4270

**Canada - Toronto** Tel: 905-695-1980 Fax: 905-695-2078

#### ASIA/PACIFIC

Australia - Sydney Tel: 61-2-9868-6733

**China - Beijing** Tel: 86-10-8569-7000

**China - Chengdu** Tel: 86-28-8665-5511

**China - Chongqing** Tel: 86-23-8980-9588

**China - Dongguan** Tel: 86-769-8702-9880

**China - Guangzhou** Tel: 86-20-8755-8029

**China - Hangzhou** Tel: 86-571-8792-8115

China - Hong Kong SAR Tel: 852-2943-5100

**China - Nanjing** Tel: 86-25-8473-2460

China - Qingdao Tel: 86-532-8502-7355

**China - Shanghai** Tel: 86-21-3326-8000

**China - Shenyang** Tel: 86-24-2334-2829

**China - Shenzhen** Tel: 86-755-8864-2200

China - Suzhou

Tel: 86-186-6233-1526 China - Wuhan

Tel: 86-27-5980-5300 China - Xian

Tel: 86-29-8833-7252

**China - Xiamen** Tel: 86-592-2388138

**China - Zhuhai** Tel: 86-756-3210040

#### ASIA/PACIFIC

India - Bangalore Tel: 91-80-3090-4444

India - New Delhi Tel: 91-11-4160-8631

India - Pune Tel: 91-20-4121-0141

Japan - Osaka

Tel: 81-6-6152-7160 Japan - Tokyo

Tel: 81-3-6880- 3770

Korea - Daegu Tel: 82-53-744-4301

Korea - Seoul Tel: 82-2-554-7200

Malaysia - Kuala Lumpur Tel: 60-3-7651-7906

Malaysia - Penang Tel: 60-4-227-8870

Philippines - Manila Tel: 63-2-634-9065

**Singapore** Tel: 65-6334-8870

**Taiwan - Hsin Chu** Tel: 886-3-577-8366

Taiwan - Kaohsiung Tel: 886-7-213-7830

**Taiwan - Taipei** Tel: 886-2-2508-8600

Thailand - Bangkok Tel: 66-2-694-1351

Vietnam - Ho Chi Minh Tel: 84-28-5448-2100

#### **EUROPE**

**Austria - Wels** Tel: 43-7242-2244-39

Fax: 43-7242-2244-393

Denmark - Copenhagen Tel: 45-4450-2828

Fax: 45-4485-2829 **Finland - Espoo** Tel: 358-9-4520-820

France - Paris

Tel: 33-1-69-53-63-20 Fax: 33-1-69-30-90-79

Germany - Garching Tel: 49-8931-9700

**Germany - Haan** Tel: 49-2129-3766400

Germany - Heilbronn Tel: 49-7131-72400

Germany - Karlsruhe Tel: 49-721-625370

**Germany - Munich** Tel: 49-89-627-144-0 Fax: 49-89-627-144-44

Germany - Rosenheim Tel: 49-8031-354-560

Israel - Ra'anana Tel: 972-9-744-7705

Italy - Milan Tel: 39-0331-742611 Fax: 39-0331-466781

Italy - Padova Tel: 39-049-7625286

**Netherlands - Drunen** Tel: 31-416-690399 Fax: 31-416-690340

Norway - Trondheim Tel: 47-7288-4388

**Poland - Warsaw** Tel: 48-22-3325737

Romania - Bucharest Tel: 40-21-407-87-50

**Spain - Madrid** Tel: 34-91-708-08-90 Fax: 34-91-708-08-91

Sweden - Gothenberg Tel: 46-31-704-60-40

Sweden - Stockholm Tel: 46-8-5090-4654

**UK - Wokingham** Tel: 44-118-921-5800 Fax: 44-118-921-5820